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**Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only**

EFS ID: 19372  
Application ID: 10065568  
Title of Invention: SOLDER BUMP STRUCTURE AND  
LASER REPAIR PROCESS FOR  
MEMORY DEVICE  
First Named Inventor: Kuo-Ming Chen  
Domestic/Foreign Application: Domestic Application  
Filing Date: null  
Effective Receipt Date: 2002-10-31  
Submission Type: Utility Patent Filing  
Filing Type: new-utility  
Confirmation Number: 0  
Attorney Docket Number: NAUP0482USA  
Digital Certificate Holder: cn=Winston Hsu, ou=Registered Attorneys, ou=Patent and  
Trademark Office, ou=Department of Commerce, o=U.S.  
Government, c=US  
Certificate Message Digest: zq0+veBWgFxxKnpwjk/UGA==  
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Payment Category: DA - Deposit Account  
Deposit Account Number: 500801  
Deposit Account Name: WINSTON HSU



# TRANSMITTAL FORM



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Stylesheet Version: 1.0

Submission Type: Utility  
Patent Filing

Attorney Docket  
Number:

NAUP0482USA

## SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR MEMORY DEVICE

First Named Inventor: Kuo-Ming Chen

### SUBMITTED BY

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Electronic Signature Mark: Mord Michael Lewis	Date Signed: 20021031

*I certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.*

*I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.*

**Attached Files:**

declaration	NAUP0482DEC1.TIF
declaration	NAUP0482DEC2.TIF
specification	NAUP0482.xml
bibd-transmittal	NAUP0482apds.xml
patent-assignments	NAUP0482asgn.xml
fee-transmittal	NAUP0482fee.xml

**Attached Image File(s):**

NAUP0482DEC1.TIF  
NAUP0482DEC2.TIF

Comments:

PATENT  
Docket No. NAU04821/USA

COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that

I believe I am the sole (if only one name appears below), or joint (if more than one name appears), original and first inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

"SOLDER BUMP STRUCTURE AND LASER REPAIR PROCESS FOR  
MEMORY DEVICE"

+ The specification for the above entitled invention is filed herewith.

The specification for the above entitled invention was filed previously  
with application serial number, Filing Date

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of the invention disclosed in this application in accordance with Title 37, Code of Federal Regulations, Section 1.56 (a). I further acknowledge the duty in any continuation-in-part application to disclose to the Patent and Trademark Office all information known to be material to the patentability of the invention disclosed in this application, as defined in 1.56, which became available to me between the filing date of the prior application and the filing date of this application.

PRIORITY CLAIM

+ There is no claim of priority

Claim of priority is based on the following:

POWER OF ATTORNEY

As a named inventor, I hereby appoint the following attorneys to prosecute this application and to transact all related business in the Patent and Trademark Office

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**DECLARATION**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued hereon

Date: Oct 16, 2002 Kuo-Ming Chen  
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# FEE TRANSMITTAL

Electronic Version 1.1.0

Stylesheet Version: 1.0

*Patent fees are subject to annual revisions on or about October 1st of each year.*

Large Entity

**TOTAL FEES AUTHORIZED: \$ 780**

The commissioner is hereby authorized to charge indicated processing and/or publication fees and credit any overpayments to:

Deposit Account Number: 500801

Deposit Account Name: NORTH AMERICA INTERNATIONAL PATENT OFFICE



Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

## SUBMITTED BY

Authorized Name: WINSTON HSU  
Electronic Signature Mark: VAEB-JMXX-8IIL  
Date Signed: 20021031

## BASIC FILING FEE

Fee Description	Fee Code	Fee Paid
Utility Filing Fee	1001	\$ 740

Subtotal For Basic Filing Fee: \$ 740

## EXTRA CLAIM FEES

	Fee Code	Fee	Extra Claims	Fee Paid
Total Claims: 10	1202	\$ 18	0	\$ 0
Independent Claims: 3	1201	\$ 84	0	\$ 0

